

HT82M23A/HT82M23B/HT82M23C

3/5-Key USB+PS/2 Optical Mouse Controller

Features

- Operating voltage: 4.4V~5.25V
- Compatible with Microsoft Windows 2000 and 5-button Wheel Mouse
- Microsoft 3D Intelli mouse and IBM PS/2 mouse compatible
- Supports 3/5 buttons and Z-axis input
- Z-axis can support two kinds of scroller input (optomechanical and mechanical)
- 3 key or 5 key mode can be selected by package
- Complete Universal Serial Bus specs V2.0 compatibility
- Serial Bus Interface Engine (SIE)
- · USB transceiver
- Single chip solution especially for USB mouse function

- HALT function and wake-up feature reduce power consumption
- · Plug and Play functions
- · Minimal external components
- · 6MHz crystal oscillator for system clock
- Interface compliant with ADNS-2051, ADNS-2610 and ADNS-2620
- · Pass WHQL, USB-IF and EMC testing
- HT82M23A is pin compatible with HT82M22A
- HT82M23B/HT82M23C is pin compatible with HT82M21A
- HT82M23A: 20-pin DIP/SOP package HT82M23B/HT82M23C: 18-pin DIP/SOP package

General Description

HT82M23A/HT82M23B/HT82M23C is a Plug and Play Windows 2000 and 5-button 3D USB+PS/2 Mouse controller. The HT82M23A/HT82M23B/HT82M23C can support the USB Standard Request as well as HID Class Request version 1.1. It is compatible with Microsoft Intelli 3D or Windows 2000 5 key PS/2 mouse. The Z-axis can support two kinds of scroller input, namely; mechanical and optomechanical. It requires minimal external com-

ponents to implement 3D or Windows 2000 5 key USB plus PS/2 mouse. All its features combined and make up this versatile Holtek 8-bit MCU with an on-chip USB interface logic. The USB is specified by the Universal Serial Bus Specification V2.0.

The USB vendor ID for HT82M23A/HT82M23B/ HT82M23C is defined as 04D9H, the USB product ID is different by different package

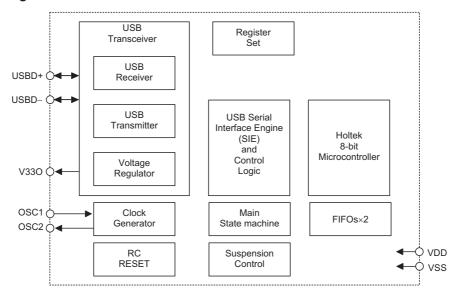
Selection Table

Part No.	Interface	Mode	USB Product ID	Package
HT82M23A	USB and PS/2	Windows 2000	048EH	20DIP/SOP
HT82M23B	USB and PS/2	3D	0499H	18DIP/SOP
HT82M23C	USB only	3D	0499H	18DIP/SOP

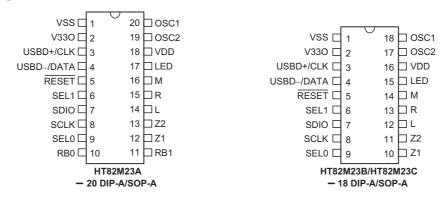
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Block Diagram



Pin Assignment



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HT82M23A/HT82M23B/HT82M23C

Pin Description

Pin Name	I/O	Description
VSS	_	Negative power supply, ground
V33O	0	3.3V voltage output
USBD+/CLK	I/O	USB data plus or PS2 Clock, F/W auto-detect USBD+ for USB, CLK for PS2
USBD-/DATA	I/O	USB data minus or PS2 Data, F/W auto-detect USB- for USB, DATA for PS2
RESET	I	Chip reset input, low active
SEL1 SEL0	I	Configuration selections SEL1=0: Z-axis is divided by 2 (default) SEL1=1: Z-axis is divided by 4 For ADNS 2051: SEL0=0: 800DPI (default) SEL0=1: 400DPI For ADNS 2610/2620: SEL0=0, 400DPI (default) SEL0=1, 800DPI-by firmware
SDIO	I/O	Serial data for Agilent sensor IC SDIO
SCLK	I	Serial data for Agilent sensor IC SCLK
RB0, RB1 L, R, M	I	Click button detection. Input ports with $30k\Omega$ pull-high resistor. Input ports with pull-high resistor. These pads can function as Left, Right, Middle, B4 and B5 button input lines.
Z1, Z2	I	Z-axis input supports two kinds of scroller input; optomechanical and mechanical.
LED	I/O	Drives LED output
VDD	_	5V positive power supply
OSC2	0	6MHz OSC output
OSC1	I	6MHz OSC input

Absolute Maximum Ratings

Supply VoltageV _{SS} -0.3V to V _{SS} +6V	Storage Temperature50°C to 125°C
MCU Input VoltageV _{SS} -0.3 V to V _{DD} +0.3V	Operating Temperature25°C to 70°C
USB Input VoltageV _{SS} -0.3V to V _{33O} +0.3V	

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

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D.C. Characteristics

Ta=25°C

Comple at	Danamatan	Parameter Test Conditions				T	Marri	Unit	
Symbol Parameter		V _{DD}	Conditions		Min.	Тур.	Max.	Offic	
V_{DD}	Operating Voltage	_		_	4.4	_	5.25	V	
	Operating Current	5 \/	No load,	USB mode	_	10	_	mA	
I _{DD}	(Crystal OSC)	5V	f _{SYS} =6MHz	PS/2 mode	_	3	_	mA	
I _{SUS}	USB Suspend Mode	5V	No load, system HALT		_	_	250	μΑ	
V _{IL1}	Input Low Voltage (Z1, Z2, L, M, R)	5V	_		0	_	1.0	V	
V _{IH1}	Input High Voltage (Z1, Z2, L, M, R)	5V		_	3.5	_	5	V	
V _{IL2}	Input Low Voltage (RESET)	5V			0	_	1.5	V	
V _{IH2}	Input High Voltage (RESET)	5V	_		3.5	_	5	V	
V _{POR}	Built-in Power on Reset V _{DD} Detection Voltage	5V	_		_	3.7	_	V	
I _{OL}	Sink Current (LED)	5V	V _{OL} =0.8V		_	50	_	mA	

A.C. Characteristics

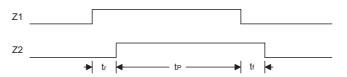
Ta=25°C

Symbol	Parameter		Test Conditions	Min.	Тур.	Max.	Unit
Symbol	Parameter	V_{DD}	Conditions	IVIIII.		wax.	Unit
f _{SYS}	System Clock (Crystal OSC)	5V	_	0	6000	_	kHz

Note: t_{SYS}=1/f_{SYS}

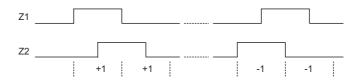
Timing Diagram

Z-axis Photo-Coupler Crossed Width



Note: For Z-axis t_r , t_P , $t_f > 1 ms$

Z-axis Counting



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Functional Description

PS/2 Mouse

- PS/2 status byte
 - Byte 1

Bit 7: Reserved

Bit 6: 0=Stream Mode, 1=Remote Mode

Bit 5: 0=Disabled, 1=Enabled

Bit 4: 0=Scaling 1:1, 1=Scaling 2:1

Bit 3: 1=Wrap Mode, 0=Stream or Remote (different from IBM specs.)

Bit 2: 1=Left Button Pressed

Bit 1: 1=Middle Button Pressed

Bit 0: 1=Right Button Pressed

Byte 2

Bit 0~7 current resolution setting (Bit 0=LSB)

• Byte 3

Bit 0~7 current sampling rate (Bit 0=LSB)

• Standard PS/2 data format (HT82M23A/HT82M23B)

Bit No.	7	6	5	4	3	2	1	0
1st word	ΥV	XV	YS	XS	1	М	R	L
2nd word	X7	X6	X5	X4	Х3	X2	X1	X0
3rd word	Y7	Y6	Y5	Y4	Y3	Y2	Y1	Y0

• Data format for 3D PS/2 (HT82M23A/HT82M23B)

Bit No.	7	6	5	4	3	2	1	0
1st word	ΥV	XV	YS	XS	1	М	R	L
2nd word	X7	X6	X5	X4	Х3	X2	X1	X0
3rd word	Y7	Y6	Y5	Y4	Y3	Y2	Y1	Y0
4th word	Z 7	Z6	Z5	Z4	Z3	Z2	Z1	Z0

Note: The X/Y data report is 9-bit 2's complement The Z data report is 8-bit 2's complement

• Data format for 5-button Wheel Mouse (HT82M23A)

Bit No.	7	6	5	4	3	2	1	0
1st word	0	0	YS	XS	1	М	R	L
2nd word	X7	X6	X5	X4	Х3	X2	X1	X0
3rd word	Y7	Y6	Y5	Y4	Y3	Y2	Y1	Y0
4th word	0	0	RB1	RB0	Z3	Z2	Z1	Z0

Note: X- movement towards the right is positive, moving towards the left is negative

Y- upward movement is positive, moving down is negative

Z-rolling towards the user is positive, else negative Button status: 1=pressed, 0=released

 For HT82M23A/HT82M23B, mouse mode changes between Standard and 3D PS/2 mode.
 Sending the commands in the following sequence will set the mouse to 3D PS/2 mode.

Command	Response From Mouse
F3h	FAh
C8h	FAh
F3h	FAh
64h	FAh
F3h	FAh
50h	FAh
F2h	FAh, 03h

 For HT82M23A, mouse mode changes between Standard and Windows 2000 PS/2 mode.
 Sending the commands in the following sequence will set the mouse to Windows 2000 PS/2 mode.

Command	Response From Mouse
F3h	FAh
C8h	FAh
F3h	FAh
C8h	FAh
F3h	FAh
50h	FAh
F2h	FAh, 04h

 Any time the PC sends a reset "FFh" command to the mouse, it will reset the mouse to Standard PS/2 mode.

After power-on reset is initiated, the mouse is set to Standard PS/2 mode.

 USB mouse data format for 3D mod (HT82M23A/HT82M23B/HT82M23C)

Bit No.	7	6	5	4	3	2	1	0
1st word	0	0	0	0	0	М	R	L
2nd word	X7	X6	X5	X4	Х3	X2	X1	X0
3rd word	Y7	Y6	Y5	Y4	Y3	Y2	Y1	Y0
4th word	Z7	Z6	Z 5	Z4	Z3	Z2	Z1	Z0

• Data format for Windows 2000 mode (HT82M23A)

Bit No.	7	6	5	4	3	2	1	0
1st word	0	0	0	RB1	RB1	М	R	L
2nd word	X7	X6	X5	X4	Х3	X2	X1	X0
3rd word	Y7	Y6	Y5	Y4	Y3	Y2	Y1	Y0
4th word	Z7	Z6	Z5	Z4	Z3	Z2	Z1	Z0

Note: X-movement towards the right is positive, moving towards the left is negative

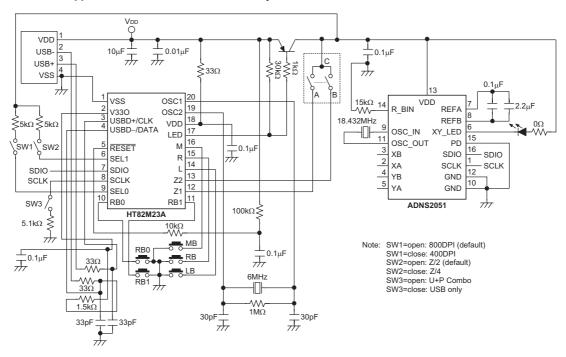
Y- upward movement is negative, moving down is positive

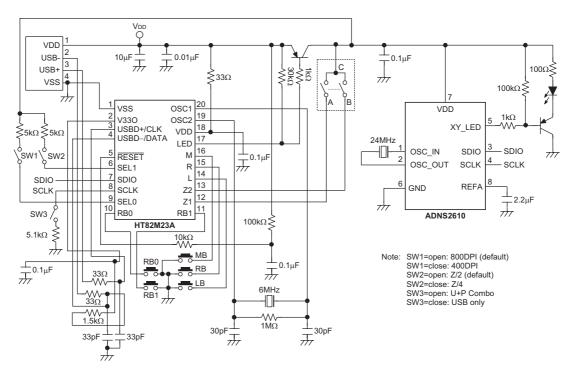
Z-rolling towards the user is negative, else positive Button status: 1=pressed, 0=released



Application Circuits

HT82M23A Application Circuit is for Reference Only



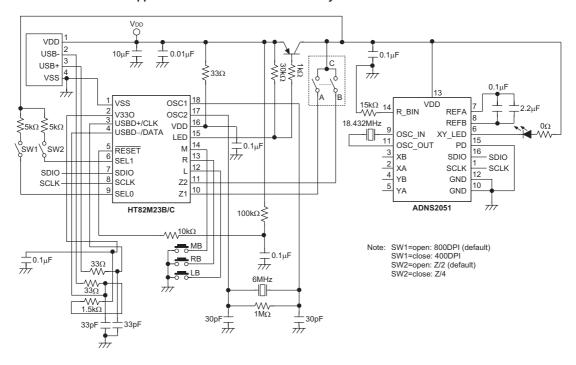


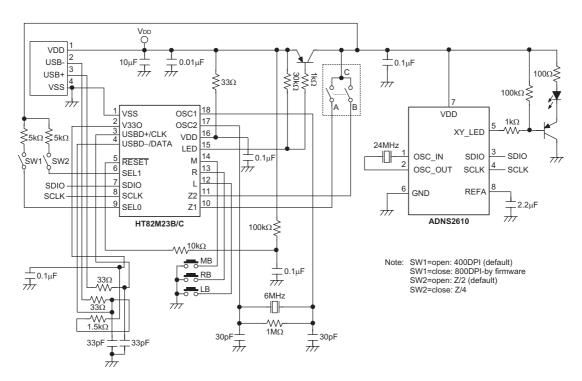
Note: Layout $0.1\mu\text{F}$ capacitor, 33Ω resistor and $0.01\mu\text{F}$ capacitor as close to VDD pin as possible.

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HT82M23B/HT82M23C Application Circuit is for Reference Only





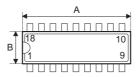
Note: Layout $0.1\mu\text{F}$ capacitor, 33Ω resistor and $0.01\mu\text{F}$ capacitor as close to VDD pin as possible.

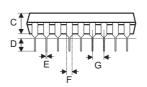
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Package Information

18-pin DIP (300mil) Outline Dimensions





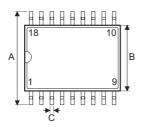


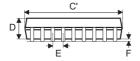
Complete	Dimensions in mil		
Symbol	Min.	Nom.	Max.
А	895	_	915
В	240	_	260
С	125	_	135
D	125	_	145
E	16	_	20
F	50	_	70
G	_	100	_
Н	295	_	315
I	335	_	375
α	0°	_	15°

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18-pin SOP (300mil) Outline Dimensions





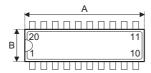


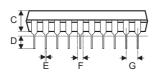
Combal	Dimensions in mil		
Symbol	Min.	Nom.	Max.
Α	394	_	419
В	290	_	300
С	14	_	20
C'	447	_	460
D	92	_	104
E	_	50	_
F	4	_	_
G	32	_	38
Н	4		12
α	0°	_	10°

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20-pin DIP (300mil) Outline Dimensions





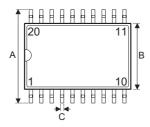


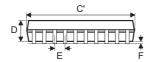
Symphol .	Dimensions in mil		
Symbol	Min.	Nom.	Max.
А	1020	_	1045
В	240	_	260
С	125	_	135
D	125	_	145
E	16	_	20
F	50	_	70
G	_	100	_
Н	295	_	315
I	335	_	375
α	0°	_	15°

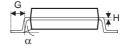
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20-pin SOP (300mil) Outline Dimensions







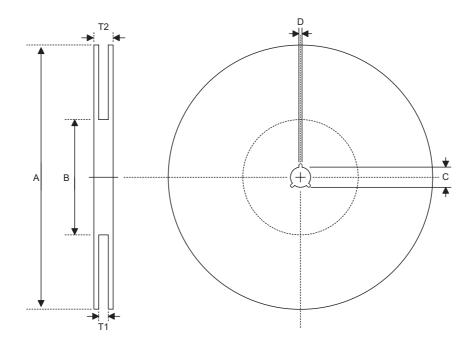
S. mhal	Dimensions in mil		
Symbol	Min.	Nom.	Max.
А	394	_	419
В	290	_	300
С	14	_	20
C'	490	_	510
D	92	_	104
E	_	50	_
F	4	_	_
G	32	_	38
Н	4	_	12
α	0°	_	10°

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Product Tape and Reel Specifications

Reel Dimensions



SOP 18W

Symbol	Description	Dimensions in mm
А	Reel Outer Diameter	330±1.0
В	Reel Inner Diameter	62±1.5
С	Spindle Hole Diameter	13.0+0.5 -0.2
D	Key Slit Width	2.0±0.5
T1	Space Between Flange	24.8+0.3 -0.2
T2	Reel Thickness	30.2±0.2

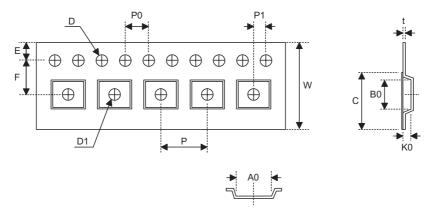
SOP 20W

Symbol	Description	Dimensions in mm
А	Reel Outer Diameter	330±1.0
В	Reel Inner Diameter	62±1.5
С	Spindle Hole Diameter	13.0+0.5 -0.2
D	Key Slit Width	2.0±0.5
T1	Space Between Flange	24.8+0.3 -0.2
T2	Reel Thickness	30.2±0.2

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Carrier Tape Dimensions



SOP 18W

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	24.0+0.3 -0.1
Р	Cavity Pitch	16.0±0.1
Е	Perforation Position	1.75±0.1
F	Cavity to Perforation (Width Direction)	11.5±0.1
D	Perforation Diameter	1.5±0.1
D1	Cavity Hole Diameter	1.5+0.25
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.0±0.1
A0	Cavity Length	10.9±0.1
В0	Cavity Width	12.0±0.1
K0	Cavity Depth	2.8±0.1
t	Carrier Tape Thickness	0.3±0.05
С	Cover Tape Width	21.3

SOP 20W

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	24.0+0.3 -0.1
Р	Cavity Pitch	12.0±0.1
Е	Perforation Position	1.75±0.1
F	Cavity to Perforation (Width Direction)	11.5±0.1
D	Perforation Diameter	1.5+0.1
D1	Cavity Hole Diameter	1.5+0.25
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.0±0.1
A0	Cavity Length	10.8±0.1
В0	Cavity Width	13.3±0.1
K0	Cavity Depth	3.2±0.1
t	Carrier Tape Thickness	0.3±0.05
С	Cover Tape Width	21.3

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